TPT-application 33µm copper bonding

**Equipment:**

- 33µm gold wire, 100m at 2” spool
- 33µm copper capillary and 33µ gold wedge
- Semiautomatic Wire Bonder HB16

**Ball Bonding process:**

- it is important that the forming gas (95%N₂/5%H₂) is on the tool during the EFO (TPT Copper Kit Option H47)
- need more Bond Force like Gold wire
- otherwise same process like Gold bonding.
- it is recommended to heat up bond surface up to 120°C.

**Wedge Bonding process:**

- need more Bond Force like Gold wire
- same process like Gold bonding.
- it is recommended to heat up bond surface up to 120°C.

**Advantages over gold bonding:**

- cheaper wire in mass production.
- better electronically conductivity.
- better thermal conductivity.